

Title (en)

SEMICONDUCTOR PACKAGE WITH TRANSPARENT LID

Title (de)

HALBLEITERKAPSELUNG MIT TRANSPARENTER KLAPPE

Title (fr)

BOITIER DE SEMI-CONDUCTEUR POSSEDANT UN COUVERCLE TRANSPARENT

Publication

EP 1894248 A2 20080305 (EN)

Application

EP 06779754 A 20060622

Priority

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- GB 0512732 A 20050622

Abstract (en)

[origin: WO2006136935A2] In an optical integrated circuit device a transparent element (106) is mounted over at least the optically active elements (102) in order to provide protection for the integrated circuit during use. The transparent element 106 is retained in position by adhesive (105). The adhesive (105) is deposited between and maintained in position by a pair of ridges (104) provided around the optically active element or elements. The ridges (104) are formed from an organic photolithographic gel.

IPC 8 full level

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CPC (source: EP)

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